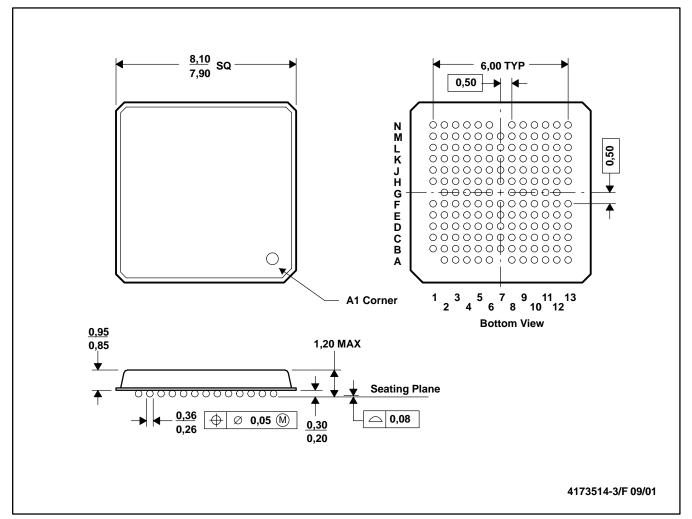
MECHANICAL DATA

MPBG151D - JULY 2000 - REVISED SEPTEMBER 2001

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

GJJ (S-PBGA-N163)

- B. This drawing is subject to change without notice.
- C. MicroStar BGA™ configuration

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